

BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC3231GV$

GENERAL PURPOSE 5 V 100 MHz AGC AMPLIFIER

DESCRIPTION

The μ PC3231GV is a silicon monolithic IC designed for use as AGC amplifier for digital CATV, cable modem and digital terrestrial systems. This IC consists of gain control amplifier and video amplifier.

The package is 8-pin SSOP (Shrink Small Outline Package) suitable for surface mount.

This IC is manufactured using our 30 GHz fmax UHS0 (Ultra High Speed Process) silicon bipolar process.

This process uses silicon nitride passivation film. This material can protect chip surface from external pollution and prevent corrosion/migration. Thus, this IC has excellent performance, uniformity and reliability.

FEATURES

- Low distortion : IM₃ = 53.5 dBc TYP. @ single-ended output, $V_{out} = 105 dB\mu V (0.5 V_{P-P})$ /tone
- Low noise figure : NF = 5.0 dB TYP. @ maximum gain
- Wide AGC dynamic range
 - : GCRin = 61 dB TYP. @ input prescribe
- On-chip video amplifier : Vout = 1.0 Vp-p TYP. @ single-ended output
- Supply voltage : Vcc = 5.0 V TYP.
- Packaged in 8-pin SSOP suitable for surface mounting

APPLICATION

• Digital terrestrial TV/Digital CATV/Cable modem receivers

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
<i>µ</i> РС3231GV-E1	μΡC3231GV-E1-A	8-pin plastic SSOP (4.45 mm (175)) (Pb-Free)	3231	 Embossed tape 8 mm wide Pin 1 indicates pull-out direction of tape Qty 1 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: *µ*PC3231GV-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

INTERNAL BLOCK DIAGRAM AND PIN CONNECTIONS



PRODUCT LINE-UP OF 5 V AGC AMPLIFIER

Part Number	lcc (mA)	Gмах (dB)	Gміn (dB)	GCR (dB)	NF (dB)	IM₃ (dBc)	Package
μPC3217GV	23	53	0	53	6.5	50 Note1	8-pin SSOP (4.45 mm (175))
μPC3218GV	23	63	10	53	3.5	50 Note1	
μPC3219GV	36.5	42.5	0	42.5	9.0	58 Note1	
μPC3221GV	33	60	10	50	4.2	56 ^{Note1}	
μPC3231GV	36	65	4	61	5.0	53.5 ^{Note2}	

Notes 1. f1 = 44 MHz, f2 = 45 MHz, $V_{out} = 0.7 V_{p-p}$ /tone, single-ended output **2.** f1 = 44 MHz, f2 = 45 MHz, $V_{out} = 0.5 V_{p-p}$ /tone, single-ended output

PIN EXPLANATIONS

Pin No.	Pin Name	Applied Voltage (V)	Pin Voltage (V) ^{Note}	Function and Application	Internal Equivalent Circuit
1	Vcc	4.5 to 5.5	_	Power supply pin. This pin should be externally equipped with bypass capacitor to minimize	
2	INPUT1	_	1.32	ground impedance. Signal input pins to AGC amplifier. This pin should be coupled with capacitor for DC cut.	AGC Control
3	INPUT2	_	1.32		
4	Vage	0 to Vcc	_	Gain control pin. This pin's bias govern the AGC output level. Minimum Gain at V _{AGC} : 0 to 0.1 V Maximum Gain at V _{AGC} : 2.7 to 3.3 V Recommended to use AGC voltage with externally resister (example: 1 kΩ).	1 4 4 4 4 4 5 5 5 6 6 6 6 6 6 6 6 6 6 6 6 6
5	GND2	0	_	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible.	
6	OUTPUT2	_	1.91	Signal output pins of video amplifier. This pin should be coupled with capacitor for DC cut.	
7	OUTPUT1	_	1.91		
8	GND1	0	_	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All ground pins must be connected together with wide ground pattern to decrease impedance difference.	

Note Pin voltage is measured at Vcc = 5.0 V.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	Vcc	T _A = +25°C	6.0	V
Gain Control Voltage Range	VAGC	T _A = +25°C	0 to Vcc	V
Power Dissipation	PD	T _A = +85°C Note	250	mW
Storage Temperature	Tstg		–55 to +150	°C

Note Mounted on double-sided copper-clad 50 \times 50 \times 1.6 mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc		4.5	5.0	5.5	V
Operating Ambient Temperature	TA	Vcc = 4.5 to 5.5 V	-40	+25	+85	°C
Gain Control Voltage Range	VAGC		0	-	3.3	V
Operating Frequency Range	fвw		30	I	90	MHz

ELECTRICAL CHARACTERISTICS

(TA = +25°C, Vcc = 5 V, f = 45 MHz, Zs = 50 Ω , ZL = 250 Ω , single-ended output)

Parameter	Symbol	Test Conditions		MIN.	TYP.	MAX.	Unit
DC Characteristics							
Circuit Current	lcc	Vcc = 5 V, No input signal	Note 1	28	36	44	mA
AGC Voltage High Level	VAGC (H)	@ Maximum gain	Note 1	2.7	_	3.3	V
AGC Voltage Low Level	VAGC (L)	@ Minimum gain	Note 1	0	-	0.1	V
RF Characteristics							
IF Input Voltage Range	fIFin	fc = -3 dB	Note 1	30	-	90	MHz
Maximum Voltage Gain	Gmax	$V_{AGC} = 2.7 \text{ V}, \text{ Pin} = -60 \text{ dBm}$	Note 1	62.5	65	67.5	dB
Minimum Voltage Gain	Gmin	$V_{AGC} = 0.1 \text{ V}, \text{ Pin} = -30 \text{ dBm}$	Note 1	0	4	7	dB
Gain Control Range (input prescribe)	GCRin	VAGC = 0.1 to 2.7 V	Note 1	55.5	61	-	dB
Gain Control Range (output prescribe)	GCRout	Vout = 1.0 Vp-p	Note 1	45	55	-	dB
Output Voltage	Vout	$P_{in} = -61$ to -6 dBm	Note 1	-	1.0	-	V _{p-p}
Maximum Output Voltage	Voclip	Vagc = 3.0 V	Note 1	2.0	3.3	-	V _{p-p}
Noise Figure	NF	Vagc = 3.0 V	Note 2	-	5.0	6.5	dB
3rd Order Intermodulation Distortion	IМз	f1 = 44 MHz, f2 = 45 MHz, P _{in} = -20 dBm/tone, V _{out} = 105 dB μ V (0.5 V _P -p) /tor	ne Note 1	50	53.5	_	dBc
Input Impedance	Zin	VAGC = 0 V	Note 3	-	1.35//6	-	kΩ//pF

Notes 1. By measurement circuit 1

2. By measurement circuit 2

3. By measurement circuit 3

MEASUREMENT CIRCUIT 1



Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 2



Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 3



MEASUREMENT CIRCUIT 4 (PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT)



Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)



MEASUREMENT CIRCUIT 5 (PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT)

Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 6 (PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT)



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD (MEASUREMENT CIRCUIT 1)



Note Balun Transformer

Remarks

- 1. Back side: GND pattern
- 2. Au plated on pattern
- 3. •O: Through hole

TYPICAL CHARACTERISTICS (TA = $+25^{\circ}C$, unless otherwise specified)





AGC PIN CURRENT vs. GAIN CONTROL VOLTAGE RANGE



VOLTAGE GAIN vs. GAIN CONTROL VOLTAGE RANGE



Remark The graphs indicate nominal characteristics.







OUTPUT POWER vs. INPUT POWER



OUTPUT POWER vs. INPUT POWER



OUTPUT POWER vs. INPUT POWER



OUTPUT POWER vs. INPUT POWER



OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.



NOISE FIGURE vs. GAIN REDUCTION





NOISE FIGURE vs. GAIN CONTROL VOLTAGE RANGE



NOISE FIGURE vs. GAIN REDUCTION



OUTPUT POWER, IM3 vs. INPUT POWER







Remark The graphs indicate nominal characteristics.

S-PARAMETERS (TA = +25°C, Vcc = 5.0 V, VAGc = 0 V)

S11-FREQUENCY



19.86 nH

PACKAGE DIMENSIONS

8-PIN PLASTIC SSOP (4.45 mm (175)) (UNIT: mm)

0.65

-0.1±0.1

 $-0.3^{+0.10}_{-0.05} \oplus 0.10$ \otimes



0.5±0.2

- 0.15^{+0.10}

NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation). All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	H\$350

Caution Do not use different soldering methods together (except for partial heating).

- The information in this document is current as of May, 2007. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC Electronics products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of a customer's equipment shall be done under the full responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and "Specific".

The "Specific" quality grade applies only to NEC Electronics products developed based on a customerdesignated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.

- "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.
- "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
- "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

(Note)

- (1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majority-owned subsidiaries.
- (2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).



Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
РВВ	< 1000 PPM	Not De	etected	
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

See CEL Terms and Conditions for additional clarification of warranties and liability.

Important Information and Disclaimer: Information provided by CEL on its website or in other communications concerting the substance content of its products represents knowledge and belief as of the date that it is provided. CEL bases its knowledge and belief on information provided by third parties and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. CEL has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. CEL and CEL suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.